BCM857BV; BCM857BS; BCM857DS

PNP/PNP matched double transistors

Rev. 06 — 28 August 2009 Product data sheet

1. Product profile

1.1 General description

PNP/PNP matched double transistors in small Surface-Mounted Device (SMD) plastic packages. The transistors are fully isolated internally.

Table 1. Product overview

Type number	Package		NPN/NPN complement	Matched version of
	NXP	JEITA		
BCM857BV	SOT666	-	BCM847BV	BC857BV
BCM857BS	SOT363	SC-88	BCM847BS	BC857BS
BCM857DS	SOT457	SC-74	BCM847DS	-

1.2 Features

- Current gain matching
- Base-emitter voltage matching
- Drop-in replacement for standard double transistors

1.3 Applications

- Current mirror
- Differential amplifier

1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per transistor						
V_{CEO}	collector-emitter voltage	open base	-	-	–45	V
I_C	collector current		-	-	–100	mA
h_{FE}	DC current gain	V_{CE} = –5 V; I_C = –2 mA	200	290	450	

Table 2. Quick reference data *…continued*

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per device							
h_{FE1}/h_{FE2}	h_{FE} matching	V_{CE} = –5 V; I_C = –2 mA	[1]	0.9	1	-	
$V_{BE1}–V_{BE2}$	V_{BE} matching	V_{CE} = –5 V; I_C = –2 mA	[2]	-	-	2	mV

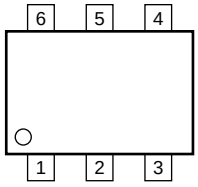
[1] The smaller of the two values is taken as the numerator.

[2] The smaller of the two values is subtracted from the larger value.

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Symbol
1	emitter TR1		
2	base TR1		
3	collector TR2		
4	emitter TR2		
5	base TR2		
6	collector TR1		



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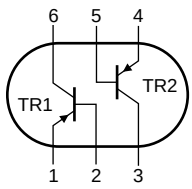

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3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
BCM857BV	-	plastic surface-mounted package; 6 leads	SOT666
BCM857BS	SC-88	plastic surface-mounted package; 6 leads	SOT363
BCM857DS	SC-74	plastic surface-mounted package (TSOP6); 6 leads	SOT457

4. Marking

Table 5. Marking codes

Type number	Marking code[1]
BCM857BV	3B
BCM857BS	A9*
BCM857DS	R8

[1] * = -: made in Hong Kong
* = p: made in Hong Kong
* = t: made in Malaysia
* = W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
Per transistor						
V_{CBO}	collector-base voltage	open emitter		-	–50	V
V_{CEO}	collector-emitter voltage	open base		-	–45	V
V_{EBO}	emitter-base voltage	open collector		-	–5	V
I_C	collector current			-	–100	mA
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms		-	–200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C				
	SOT666		[1][2]	-	200	mW
	SOT363		[1]	-	200	mW
	SOT457		[1]	-	250	mW
Per device						
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C				
	SOT666		[1][2]	-	300	mW
	SOT363		[1]	-	300	mW
	SOT457		[1]	-	380	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			–65	+150	°C
T_{stg}	storage temperature			–65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per transistor							
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air					
	SOT666		[1][2]	-	-	625	K/W
	SOT363		[1]	-	-	625	K/W
	SOT457		[1]	-	-	500	K/W

Table 7. Thermal characteristics *...continued*

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per device							
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air					
	SOT666		[1][2]	-	-	416	K/W
	SOT363		[1]	-	-	416	K/W
	SOT457		[1]	-	-	328	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

7. Characteristics

Table 8. Characteristics

T_{amb} = 25 °C unless otherwise specified

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per transistor							
I_{CBO}	collector-base cut-off current	V_{CB} = –30 V; I_E = 0 A		-	-	–15	nA
		V_{CB} = –30 V; I_E = 0 A; T_j = 150 °C		-	-	–5	µA
I_{EBO}	emitter-base cut-off current	V_{EB} = –5 V; I_C = 0 A		-	-	–100	nA
h_{FE}	DC current gain	V_{CE} = –5 V; I_C = –10 µA		-	250	-	
		V_{CE} = –5 V; I_C = –2 mA		200	290	450	
V_{CEsat}	collector-emitter saturation voltage	I_C = –10 mA; I_B = –0.5 mA		-	–50	–200	mV
		I_C = –100 mA; I_B = –5 mA		-	–200	–400	mV
V_{BEsat}	base-emitter saturation voltage	I_C = –10 mA; I_B = –0.5 mA	[1]	-	–760	-	mV
		I_C = –100 mA; I_B = –5 mA	[1]	-	–920	-	mV
V_{BE}	base-emitter voltage	V_{CE} = –5 V; I_C = –2 mA	[2]	–600	–650	–700	mV
		V_{CE} = –5 V; I_C = –10 mA	[2]	-	-	–760	mV
C_c	collector capacitance	V_{CB} = –10 V; I_E = i_e = 0 A; f = 1 MHz		-	-	2.2	pF
C_e	emitter capacitance	V_{EB} = –0.5 V; I_C = i_c = 0 A; f = 1 MHz		-	10	-	pF

Table 8. Characteristics *...continued*

T_{amb} = 25 °C unless otherwise specified

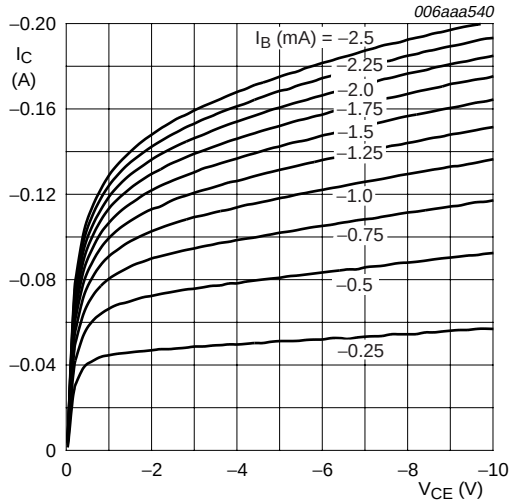
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
f_T	transition frequency	V_{CE} = –5 V; I_C = –10 mA; f = 100 MHz		100	175	-	MHz
NF	noise figure	V_{CE} = –5 V; I_C = –0.2 mA; R_S = 2 kΩ; f = 10 Hz to 15.7 kHz		-	1.6	-	dB
		V_{CE} = –5 V; I_C = –0.2 mA; R_S = 2 kΩ; f = 1 kHz; B = 200 Hz		-	3.1	-	dB
Per device							
h_{FE1}/h_{FE2}	h_{FE} matching	V_{CE} = –5 V; I_C = –2 mA	[3]	0.9	1	-	
$V_{BE1}–V_{BE2}$	V_{BE} matching	V_{CE} = –5 V; I_C = –2 mA	[4]	-	-	2	mV

[1] V_{BEsat} decreases by about 1.7 mV/K with increasing temperature.

[2] V_{BE} decreases by about 2 mV/K with increasing temperature.

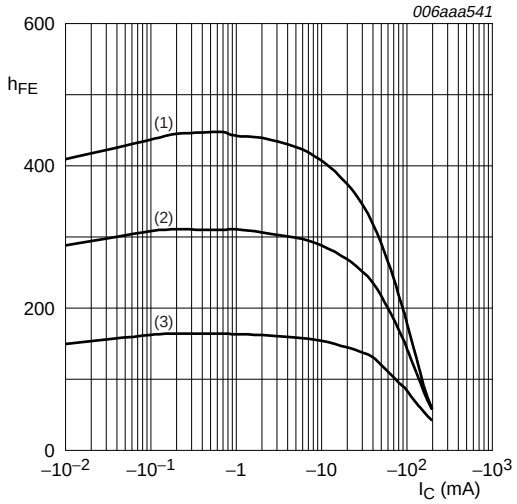
[3] The smaller of the two values is taken as the numerator.

[4] The smaller of the two values is subtracted from the larger value.



T_{amb} = 25 °C

Fig 1. Collector current as a function of collector-emitter voltage; typical values



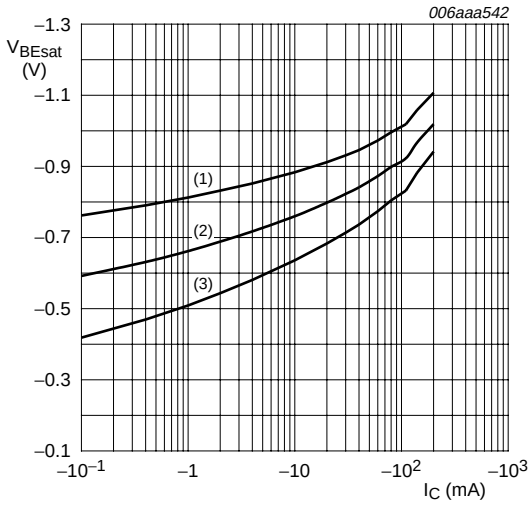
V_{CE} = −5 V

(1) T_{amb} = 100 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = −55 °C

Fig 2. DC current gain as a function of collector current; typical values



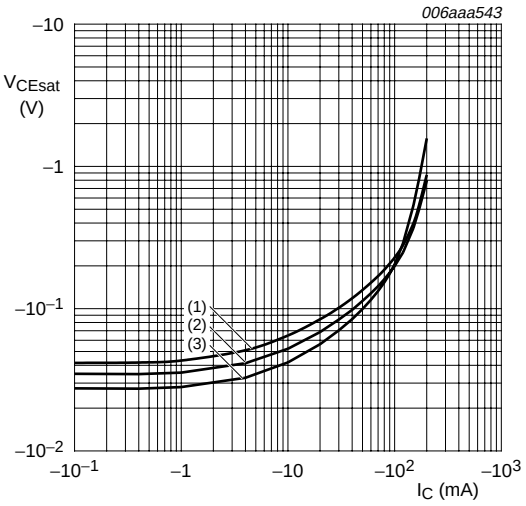
I_C/I_B = 20

(1) T_{amb} = −55 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = 100 °C

Fig 3. Base-emitter saturation voltage as a function of collector current; typical values



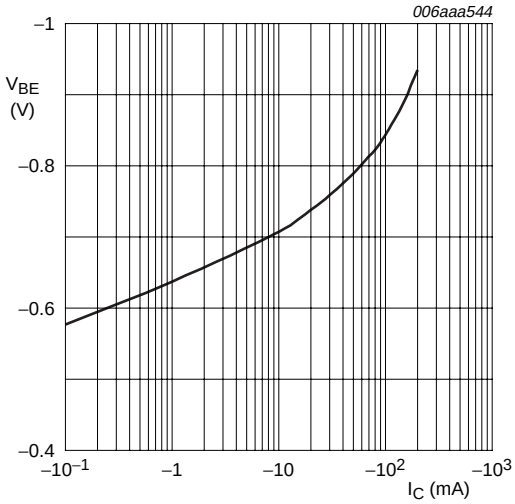
I_C/I_B = 20

(1) T_{amb} = 100 °C

(2) T_{amb} = 25 °C

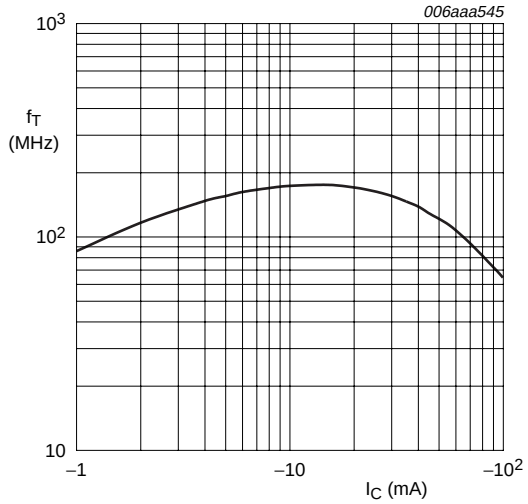
(3) T_{amb} = −55 °C

Fig 4. Collector-emitter saturation voltage as a function of collector current; typical values



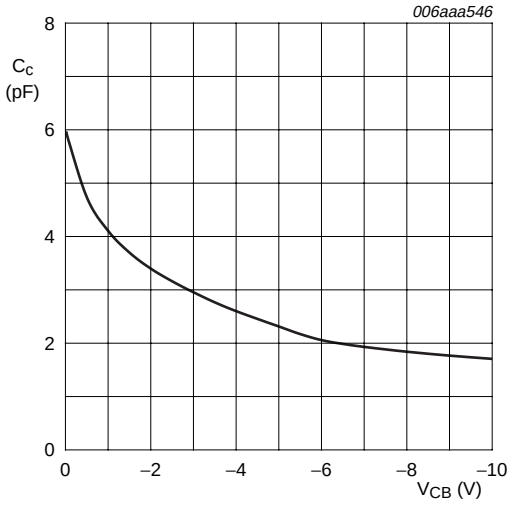
V_{CE} = –5 V; T_{amb} = 25 °C

Fig 5. Base-emitter voltage as a function of collector current; typical values



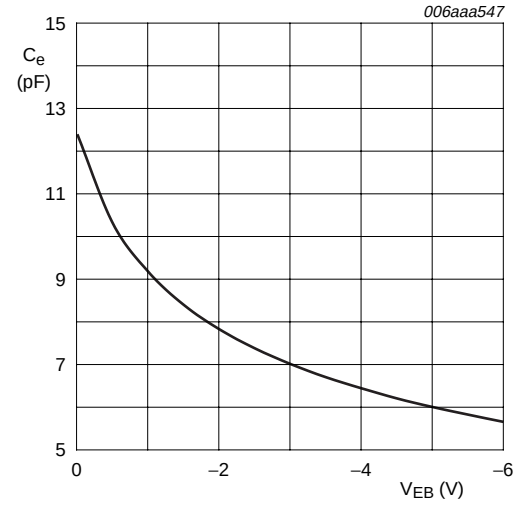
V_{CE} = –5 V; T_{amb} = 25 °C

Fig 6. Transition frequency as a function of collector current; typical values



f = 1 MHz; T_{amb} = 25 °C

Fig 7. Collector capacitance as a function of collector-base voltage; typical values



f = 1 MHz; T_{amb} = 25 °C

Fig 8. Emitter capacitance as a function of emitter-base voltage; typical values

8. Application information

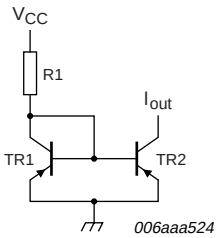


Fig 9. Current mirror

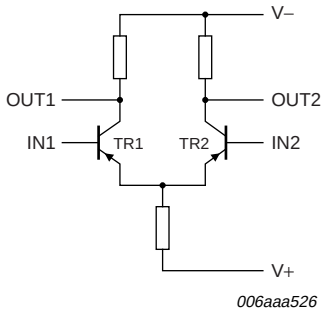


Fig 10. Differential amplifier

9. Package outline

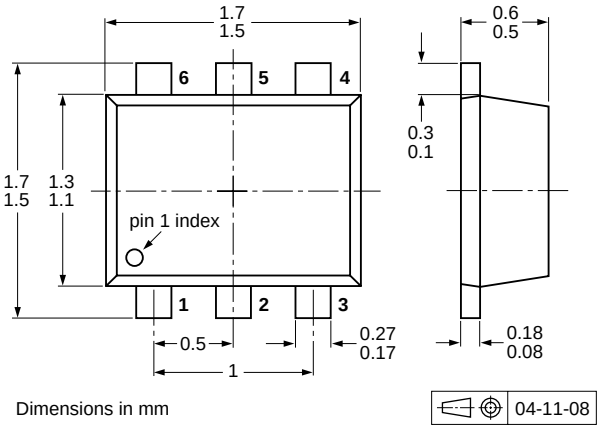


Fig 11. Package outline SOT666

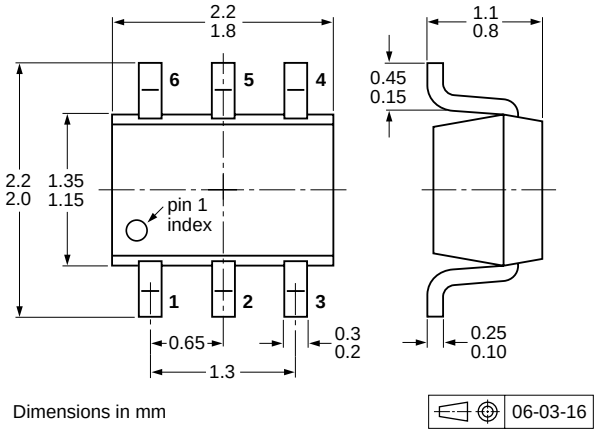


Fig 12. Package outline SOT363 (SC-88)

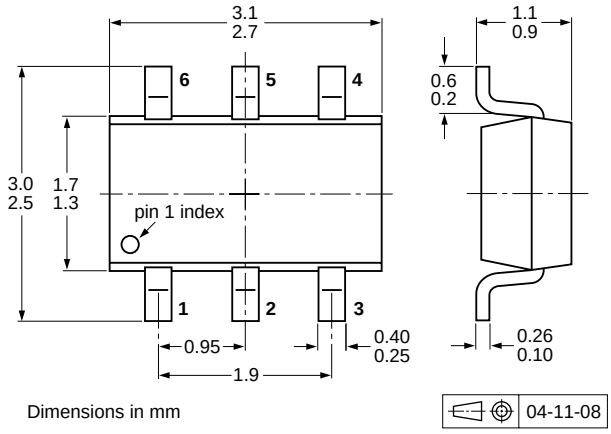


Fig 13. Package outline SOT457 (SC-74)

10. Packing information

Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

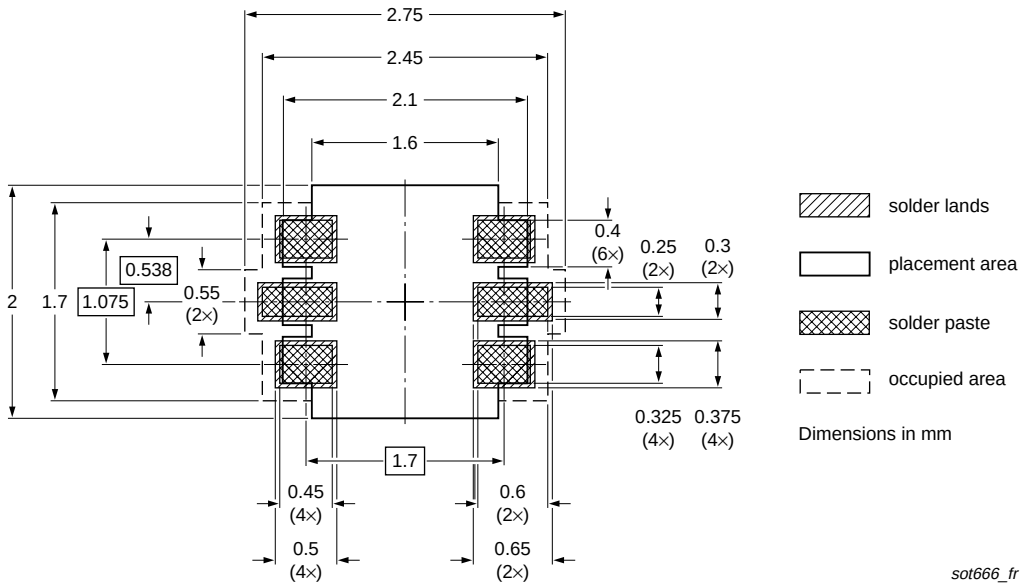
Type number	Package	Description		Packing quantity			
				3000	4000	8000	10000
BCM857BV	SOT666	2 mm pitch, 8 mm tape and reel		-	-	-315	-
		4 mm pitch, 8 mm tape and reel		-	-115	-	-
BCM857BS	SOT363	4 mm pitch, 8 mm tape and reel; T1	[2]	-115	-	-	-135
		4 mm pitch, 8 mm tape and reel; T2	[3]	-125	-	-	-165
BCM857DS	SOT457	4 mm pitch, 8 mm tape and reel; T1	[2]	-115	-	-	-135
		4 mm pitch, 8 mm tape and reel; T2	[3]	-125	-	-	-165

[1] For further information and the availability of packing methods, see Section 14.

[2] T1: normal taping

[3] T2: reverse taping

11. Soldering



Reflow soldering is the only recommended soldering method.

Fig 14. Reflow soldering footprint SOT666

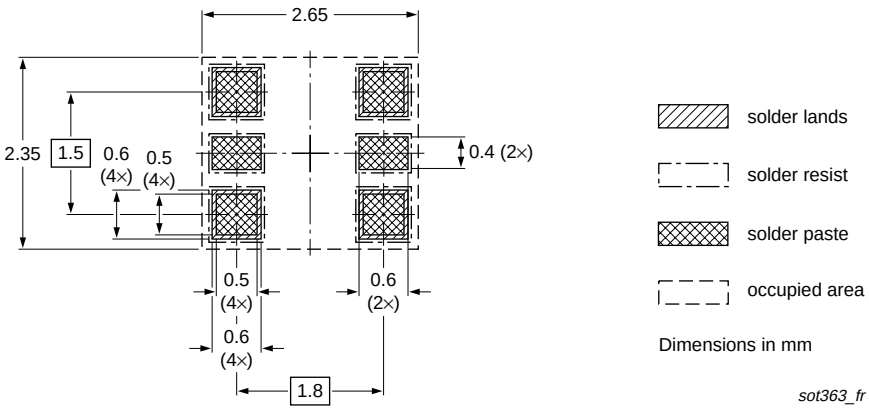


Fig 15. Reflow soldering footprint SOT363 (SC-88)

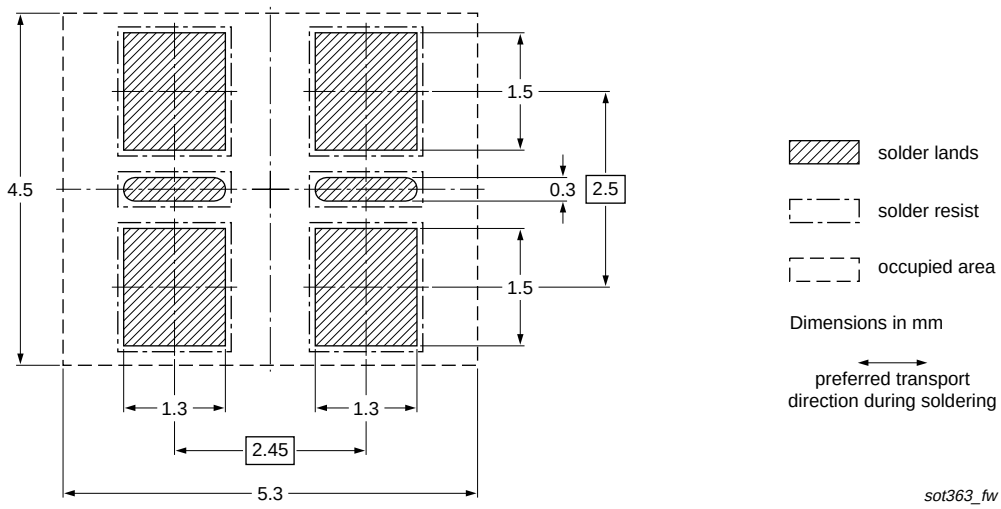
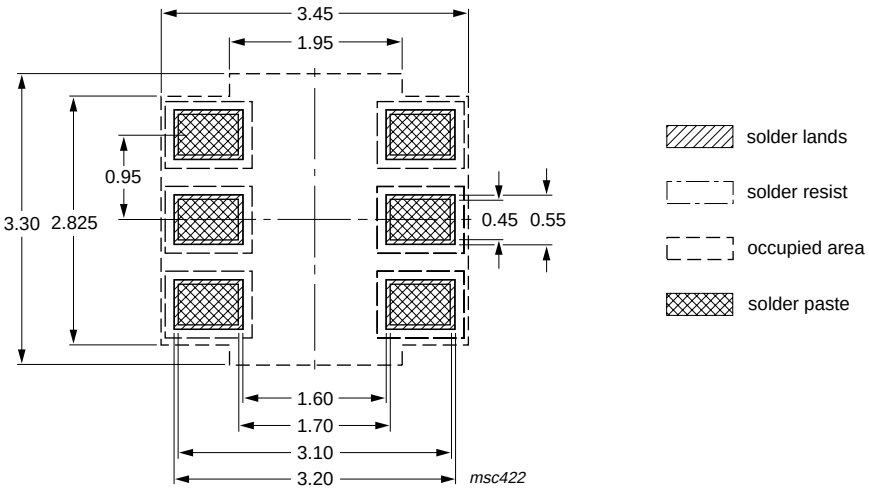
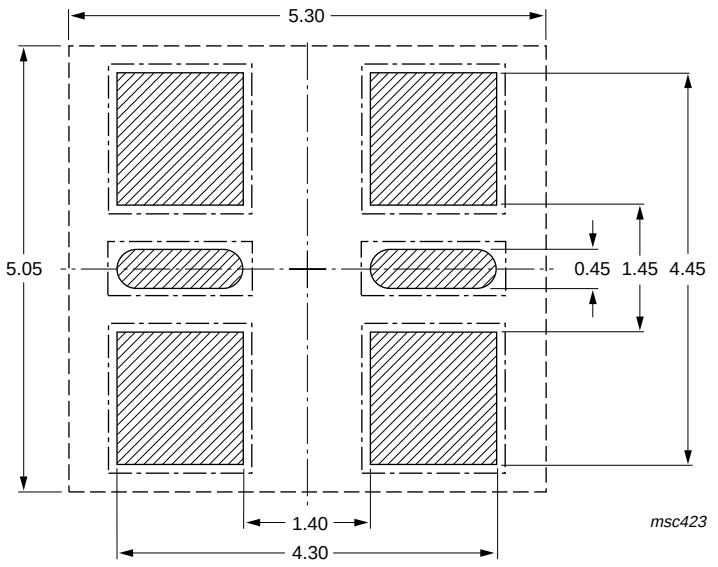


Fig 16. Wave soldering footprint SOT363 (SC-88)



Dimensions in mm

Fig 17. Reflow soldering footprint SOT457 (SC-74)



Dimensions in mm

Fig 18. Wave soldering footprint SOT457 (SC-74)

12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BCM857BV_BS_DS_6	20090828	Product data sheet	-	BCM857BV_BS_DS_5
Modifications:	• This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content. • Figure 12 “Package outline SOT363 (SC-88)”: updated • Figure 14 “Reflow soldering footprint SOT666”: updated • Figure 15 “Reflow soldering footprint SOT363 (SC-88)”: updated • Figure 16 “Wave soldering footprint SOT363 (SC-88)”: updated • Figure 18 “Wave soldering footprint SOT457 (SC-74)”: updated			
BCM857BV_BS_DS_5	20060627	Product data sheet	-	BCM857BS_DS_4
BCM857BS_DS_4	20060216	Product data sheet	-	BCM857BS_DS_3
BCM857BS_DS_3	20060130	Product data sheet	-	BCM857BS_2
BCM857BS_2	20050411	Product data sheet	-	BCM857BS_1
BCM857BS_1	20040914	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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Quick reference data — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

13.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

14. Contact information

For more information, please visit: **http://www.nxp.com**

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For more information, please visit: http://www.nxp.com
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